

**ELECTROPLATING SOLUTION CONTAINING
ORGANIC ACID COMPLEXING AGENT**

ABSTRACT

A solution for use in connection with the deposition of one or more metals on electroplatable substrates. This solution includes water; a metal ion; and a complexing agent of an organic compound having between 4 and 18 carbon atoms which includes at least two hydroxyl groups and a five or six membered ring that contains at least one oxygen atom. The complexing agent and metal ion are present in a concentration ratio of between about 3:1 and 9:1 to reduce or minimize agglomeration of the substrates during electroplating. If necessary, a suitable pH adjusting agent can be included in the solution to maintain the pH of the solution in the preferred range of between about 3.5 to 5.5, so that the solution can be used for electroplating composite articles that have electroplatable portions and non-electroplatable portions.